



Model-based Control of MOCVD Rate, Uniformity and Stoichiometry

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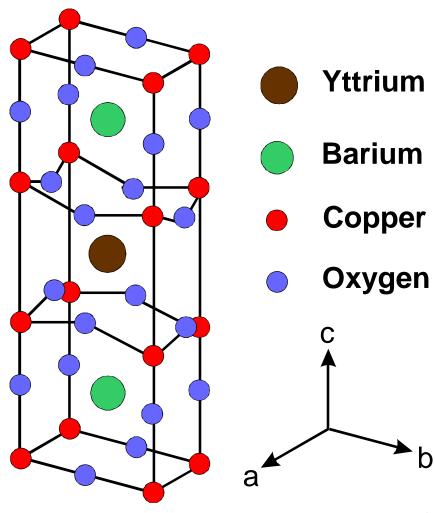




YBCO Thin Films

Fully oxygenated orthorhombic unit cell of YBa₂Cu₃O₇. At room temperature the lattice parameters are: a=3.819Å, b=3.883Å, c=11.687Å

Superconducting at temperatures as high as 93K



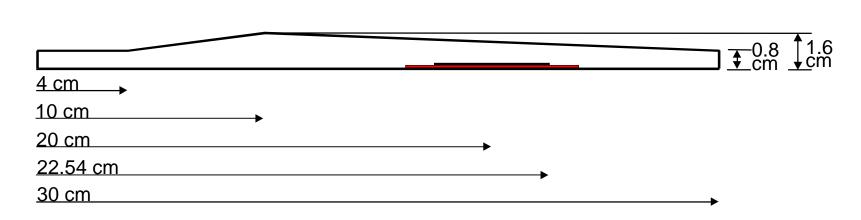




- CVD is preferable to PVD larger surfaces areas. For microwave applications (resonators, filters, antenna), a few hundred nm thick films need to be deposited on insulating substrates of diameter of at least 10 cm.
- An early challenge was finding suitable precursors for the metals. Currently, ß-diketones (general formula: RCOCH₂COR') is almost exclusively used. The ones considered here is denoted by thd (or dpm) with R=R'=C(CH₃)₃. They are vaporized at temperatures between 100-250°C, with vapor pressure between 0.01-1 Torr.







Schematic of a Thomas Swan MOCVD reactor

Steady-state operating conditions:

Gas mixture enters reactor at 10 Torr with mean velocity of 2 m/s and temperature of 240°C. The inlet mole fractions are: $O_2 = 0.44$, $N_2 = 0.47$, Ar = 0.088, $Y(dpm)_3 = 2.72 \times 10^{-5}$, $Ba(dpm)_2 = 4.41 \times 10^{-5}$, $Cu(dpm)_2 = 2.35 \times 10^{-5}$. Walls at 800°C.

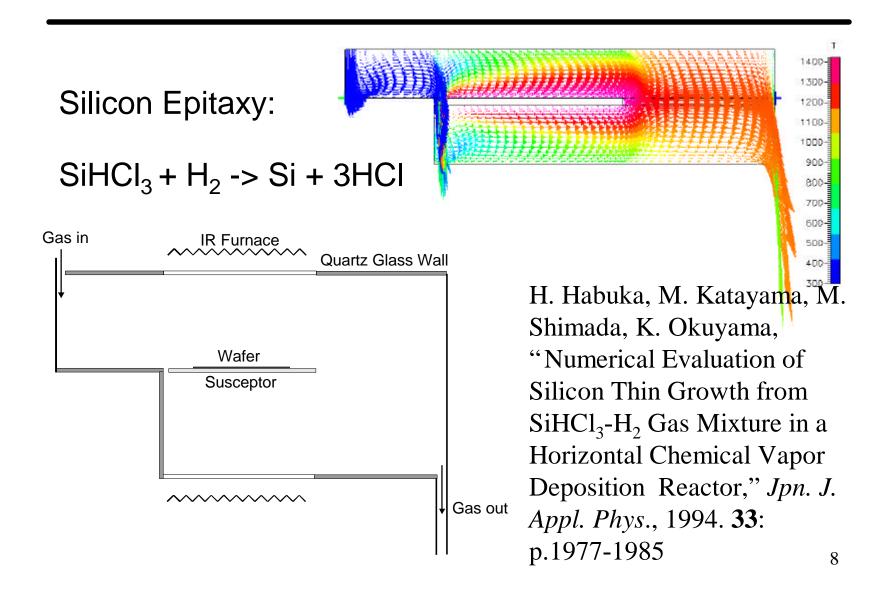




- Detailed process chemistry (gas phase and surface kinetics) is not known very well.
- Precursor decomposition, and oxide formation is currently being studied using quantum-mechanical (DFT) calculations as part of this project.
- Meantime, we are using a simplified kinetic mechanism consisting of mostly first-order finite-rate reactions for precursor decomposition, followed by very fast oxide formation. The oxides then diffuse the substrate, with surface kinetics modeled using sticking coefficients.
- CVD model developed using CFDRC's CFD-ACE[®] software



CVD Validation Study

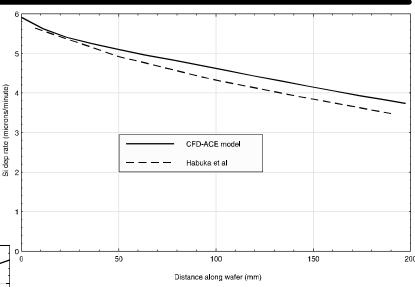


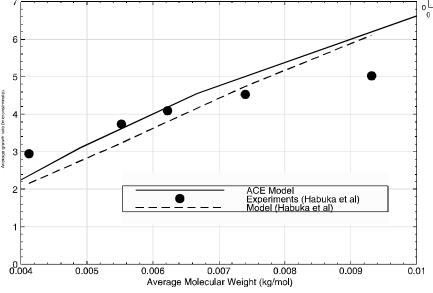




CVD Validation Study: Si Epitaxy

Model used temperaturedependent properties, Soret diffusion, multicomponent Stefan-Maxwell diffusion

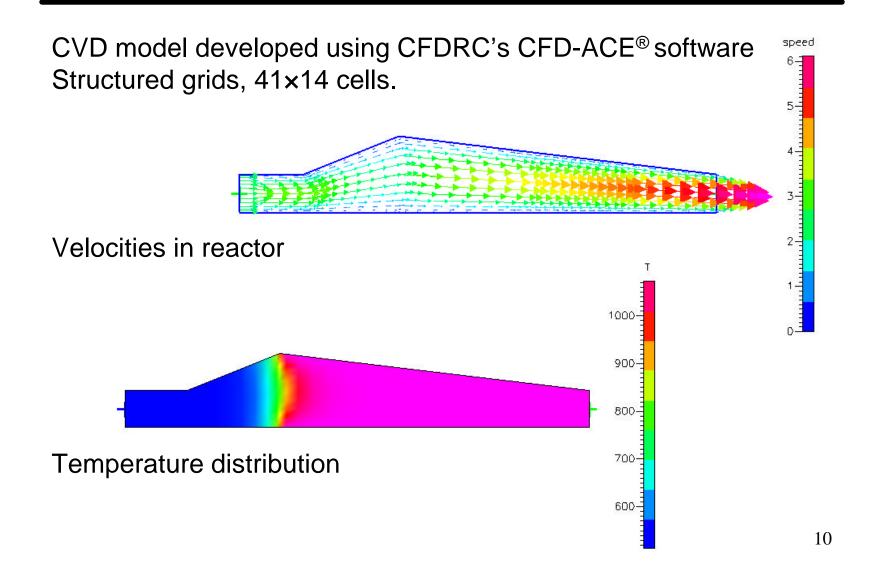




Comparison with Habuka's results for epitaxial CVD deposition show deprates within 6% of Habuka et al

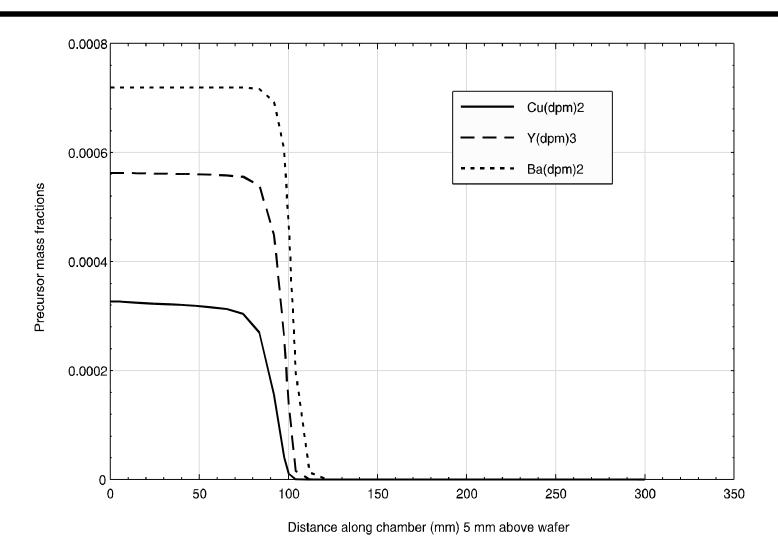






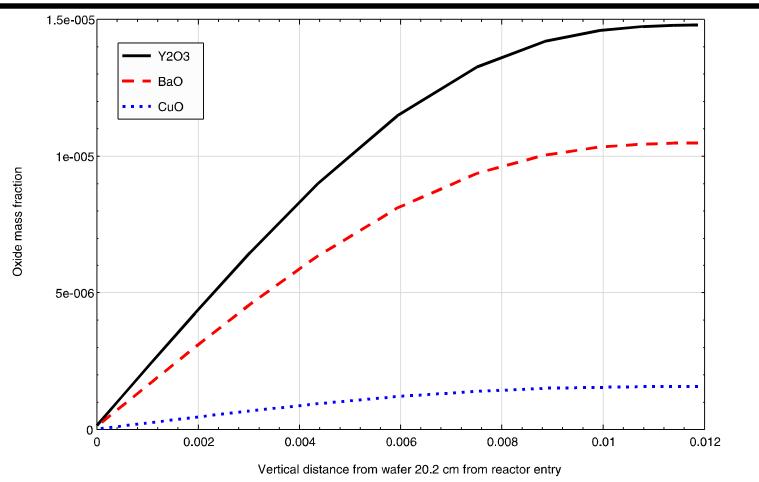








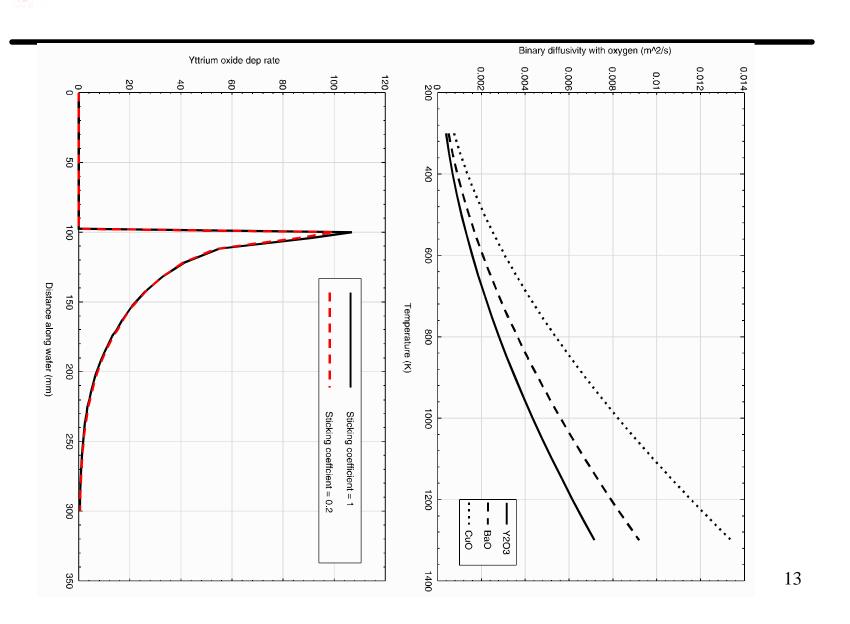




Growth occurs in a mass transport-limited regime











Chemistry:

$$Y(dpm)_3 + O_2 \rightarrow Y + 3 (dpm) + O_2$$

$$Y(dpm)_3 \rightarrow Y + 3 (dpm)$$

$$Cu(dpm)_2 \rightarrow Cu + 2 (dpm)$$

$$Ba(dpm)_2 \rightarrow Ba + 2 (dpm)$$

$$4 Y + 3 O_2 \rightarrow 2Y_2O_3$$

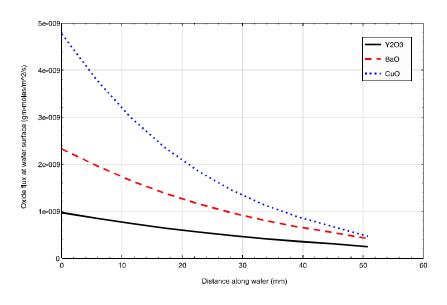
$$2 Ba + O_2 \rightarrow 2BaO$$

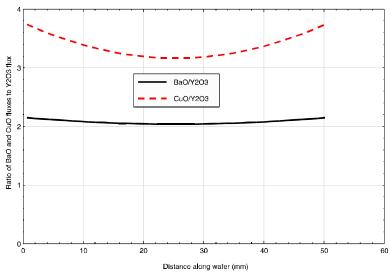
$$2 Cu + O_2 \rightarrow 2CuO$$





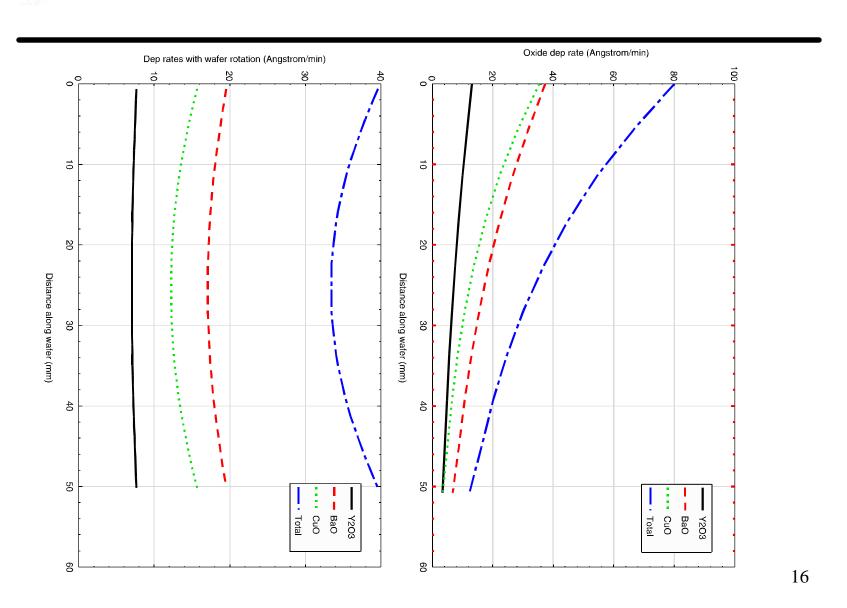
YBCO stoichiometry varies along wafer surface. Precursor concentration control can be used to restrict atom ratio within specified bounds (e.g, avoiding BaOrich deposits)







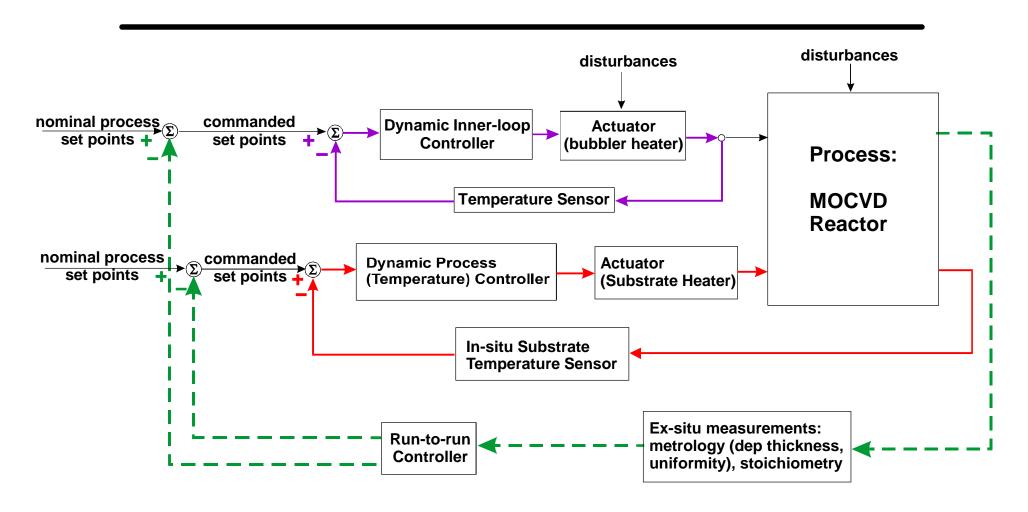








MOCVD Control Strategy







- Manufacturing: multiple copies of same product
- Product quality determined after manufacturing (run)
- Product quality is influenced by recipe variables
- Recipe variables are pre-set and fixed during the run
- Run-to-Run control problem:

Adjust recipe for next run based on results of previous runs such that product quality improves



Proportional Error Control

• Let t = 1,2,... denote run number, r_t the vector of recipe variables during run t, y_t the vector of product quality attributes at end of run t, and e_t the normalized product quality error with i-th element:

$$e_t(i) = \frac{y_t(i) - y_{des}(i)}{y_{tol}(i)}, \qquad i = 1,...,n$$

Adjust recipe according to:

$$r_t = r_{nom} + u_t,$$

 $u_t = u_{t-1} - Ge_{t-1}, \qquad u_0 = 0$





Static Linear Error System

Introduction

Assume actual process is a static linear error system:

$$e_t = w_t + Gu_t, t = 0,1,2,...$$

 w_t is vector of product quality errors due to nominal control:

$$W_t = e_t | r_t = r_{nom}$$

Error and control:

$$e_t = (I_n - GG)e_{t-1} + W_t - W_{t-1}, e_0 = W_0$$

$$u_t = (I_m - GG)u_{t-1} - GW_{t-1}, \qquad u_0 = 0$$





Static Linear Error System (cont'd)

Introduction

Note that error system is driven by *variation* in nominal error. Hence effect of biases can be eliminated, and slow drifts greatly reduced, e.g.:

then

$$W_t = b + ct + V_t$$

$$W_t - W_{t-1} = C + V_t - V_{t-1}$$

with b denoting bias, and c denoting drift rate, and v_{t} a zero-mean random variable.

However, if v_t has variance σ^2 , then $v_t - v_{t-1}$ has variance 2σ²!





Static Linear Error System

Inverse Control

• Suppose G is square (n = m) and invertible, then the stability analysis suggests the choice:

with ma real scalar.

• The error and control equation are now given by:

$$e_t = (1 - \mu)e_{t-1} + w_t - w_{t-1},$$
 $e_0 = w_0$
 $u_t = (1 - \mu)u_{t-1} - \mu G^{-1}w_{t-1},$ $u_0 = 0$

The system is stable for:

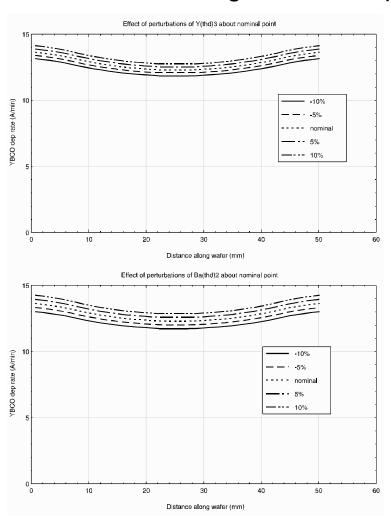
$$0 < \mu < 2$$
.

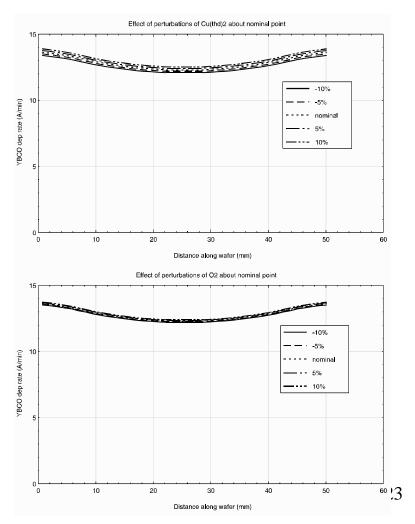




MOCVD Control

Obtaining *G* from Response Surface calculations:









Summary

- A 2D model of MOCVD reactor has been developed for deposition of YBCO thin films.
- System characterization showed the need for control of growth rate, deposition uniformity, and oxide stoichiometry at the surface.
- A run-to-run control architecture was developed, and is currently being implemented.